

S1 Passive Components Steering Committee Meeting Minutes  
 Hyatt Regency Hotel  
 Orlando, FL  
 Tuesday April 27, 2010

**1.0 Call to Order - Circulate Membership Roster**

Meeting called to order at 8:05 am by Chairman Mike Lauri.

**2.0 Committee Organization and Procedures**

2.1 Membership Intros were conducted and Roster circulated.

The attendance was as follows:

| <u>NAME</u>            | <u>COMPANY</u>    |
|------------------------|-------------------|
| Michael Lauri          | IBM               |
| Darin Glenn (by phone) | Vishay            |
| Dave Richardson        | Vishay            |
| Joe Biernacki          | SEI Electronics   |
| Laird Macomber         | CDE               |
| Brian Piscitelli       | KOA               |
| Kurt Zipp              | TC40              |
| Jayson Young           | Kemet Electronics |
| Mary Carter-Berrios    | Kemet Electronics |
| Carl Lindquist         | Guest Consultant  |
| William Gisseler       | TDK               |
| Ed Mikoski             | ECA               |
| Brian Piscatelli       | KOA               |
| Mike Cannon            | TDK               |

A quorum was present. 7 of 9 member companies present at meeting.

| <u>Member Organizations Present</u> | <u>Present at the Meeting (Spring 2010)</u> | <u>Present at this Meeting (Fall 2009)</u> | <u>Present at the Meeting (Spring 2009)</u> |
|-------------------------------------|---|--|---|
| AVX                                 | N   | N  | Y   |
| Cornell Dubilier                    | Y   | Y  | Y   |
| IBM                                 | Y   | Y  | Y   |
| Kemet                               | Y   | Y  | Y   |
| KOA Speer Electronics               | Y   | Y  | Y   |
| SEI Electronics                     | Y   | Y  | Y   |
| TDK                                 | Y   | N  | N   |
| Vishay                              | Y   | Y  | Y   |
| Murata Electronics                  | N   | Y  | Y   |

|   |
|---|
| <b><u>Other Organizations Present</u></b> |
| ECA                                       |
| TC40 TAG                                  |

**2.1 and 2.2 Approval of Agenda and Previous Minutes** – Approved Unanimously

**2.3 Correspondence** – NONE

**2.4 Review of Committees Scope-** To provide leadership and direction for passive component standards engineering working groups. The Committee will offer an opportunity for creating a unifying environment for interaction between all passive component users and producers. No changes required at this time.

### **3.0 ECA Environmental Update – ECA**

Ed Mikoski gave a report. JIG (Joint Industry Guide) 101 edition 3 is now final and will be published in April 2010. This document lists a compilation of banned material requirements for the electronics industry sector. The IPC document is more of a format and database approach but references the JIG 101. The IPC document has tiers and one of them is the JIG. Ed also talked about the QC080K which is an ISO type for management system for compliance. Page 45 of the JIG101 document lists the changes since the last revision of this document.

### 4.0 Old Business

4.1 Mike Lauri of IBM updated the group on the revision of J-STD-075 Classification of Non-IC Electronic Components for Assembly processing. This document is controlled by the ECA and the committee chairs are Paul Krystek/Mike Lauri. The spec is not going to be revised now. There was discussion about revising J-STD-075 for connectors, but the connector committee has confirmed that their parts are not PSL sensitive. The committee will probably revise this document in the 5 year review and at that time update any sections needing updates, along with adding a section on component rework. The plan is to eventually have the marking requirements moved from the J-STD-075 to J-STD-033 for clarity.

IBM asked for input on the implementation of this specification and told all the suppliers present that a new letter would be coming to them shortly so that we can get classification of all sensitive parts this year into the IBM database.

4.2 J-STD-709 - The 'Low' Halogen classification document.

A draft was balloted in December 2009 and had enough votes to pass committee, but during review at the January 2010. JC14.4 meeting, the committee agreed that the scope of the document needed to be clarified to only cover product under JEDEC's jurisdiction, solid state devices.

A limited ballot was submitted to committee members in February and has enough votes to pass. The comment resolution process is on going, but it appears that one member will not approve, thus a vote will be held at the June JC14.4 committee meeting to allow for passage of document to the JEDEC Board of Directors. If the document is forwarded on

to the Board, it could be released around the Sept. timeframe. The Board ballot is not a vote on the technical merits of the document, but whether the committee followed JEDEC procedures in the development and balloting of the document.

The 'objecting' member had petitioned the board in January on the last committee ballot, not knowing that the ballot was still in committee, so it is possible that this member may try a similar action if the 14.4 committee approves the document for a Board ballot in June. If this occurs, the date for final release of the document is in question. It could be none or it could delay release to somewhere around the end of the year. So S1 will continue to monitor this document.

4.3 Joint meetings - Did not discuss the possible joint meeting location for ECA, JEDEC and IPC in the 2010 timeframe to work on more joint standards

## **5.0 New Business**

5.1 Ed Mikoski of ECA gave a report on the activities of INEMI and agreed to help wherever possible to in drafting a roadmap for passive components. Ed proposed we pull out the 2009 passives roadmap and review it at the next S1 meeting. ECA will provide S1 committee passives portion of INEMI roadmap for review at the next meeting. Ed will call a conference call meeting as needed to review and update this information if it's prior to the next meeting in Oct 2010.

5.2 Jayson Young of Kemet gave a presentation on product environmental data compliance. Kemet is being overwhelmed with customer data requests. Kemet wanted to survey the ECA membership on who is doing what for test requirements, carbon and electrical usage reporting, and recycling reporting. Kemet was also seeking what data formats are being used and requested by the various customers. They also discussed if compliance certificates and what position level is need for signatures. Kemet is also being asked to if they support a BOM system level environmental compliance system. See the attached Kemet presentation and Kemet is looking for direct feedback from the ECA membership. KOA (Brian Piscatelli offered several insights on his company's experiences. They are resisting some customer demands that require excessive test expenses at intervals as short as 6 months and use a blanket authorization letter from management to take care of Director level signature requirements.

**6.0 Future Meetings** – The next meeting, Fall 2010, will probably be in Austin, Tx. The committee opted to let ECA pick the next Spring 2011 meeting location. With the rotation, this meeting should be held on the west coast but most companies that attend are east coast stationed.

## **8.0 Action Items** –

S1 will help support INEMI and TC40 as needed.

ECA to provide passives portion of INEMI roadmap for review before the next S1 meeting.

**9.0 Adjournment** – Meeting was adjourned at 10:00 AM.